

Title (en)

METHOD FOR APPLYING SOFT SOLDER TO A MOUNTING SURFACE OF A COMPONENT

Title (de)

VERFAHREN ZUM AUFBRINGEN VON WEICHLOT AUF EINE MONTAGEFLÄCHE EINES BAUELEMENTES

Title (fr)

PROCÉDÉ POUR APPLIQUER DU MÉTAL D'APPORT DE BRASAGE SUR UNE SURFACE DE MONTAGE D'UNE PIÈCE

Publication

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Application

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Abstract (en)

[origin: WO2011104229A1] The invention relates to a method for applying soft solder (4) to a mounting surface (10) of a component (11), wherein a) a connecting means (1) comprising a carrier layer (2) and a soft solder layer (4) formed by physical vapor deposition on the carrier layer is brought into mechanical contact between the soft solder layer (4) and the mounting surface (10), such that a first bond strength between the soft solder layer (4) and the mounting surface (10) is greater than a second bond strength between the soft solder layer (4) and the carrier layer (2), and b) the connecting means (1) is subsequently removed from the component (11) so that the carrier layer (2) releases from the soft solder layer (4) in the area of the mounting surface (10) and thus soft solder (4) remains only at the mounting surface (10).

IPC 8 full level

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See references of WO 2011104229A1

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